

TAZMO®



Wafer Support System

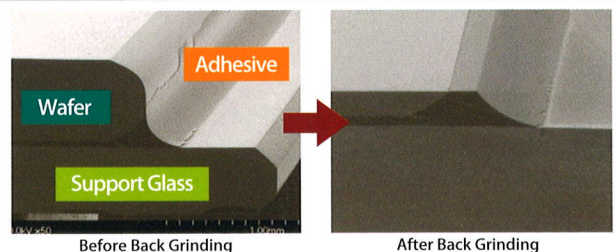
[TWS3000 SERIES]

● Overview

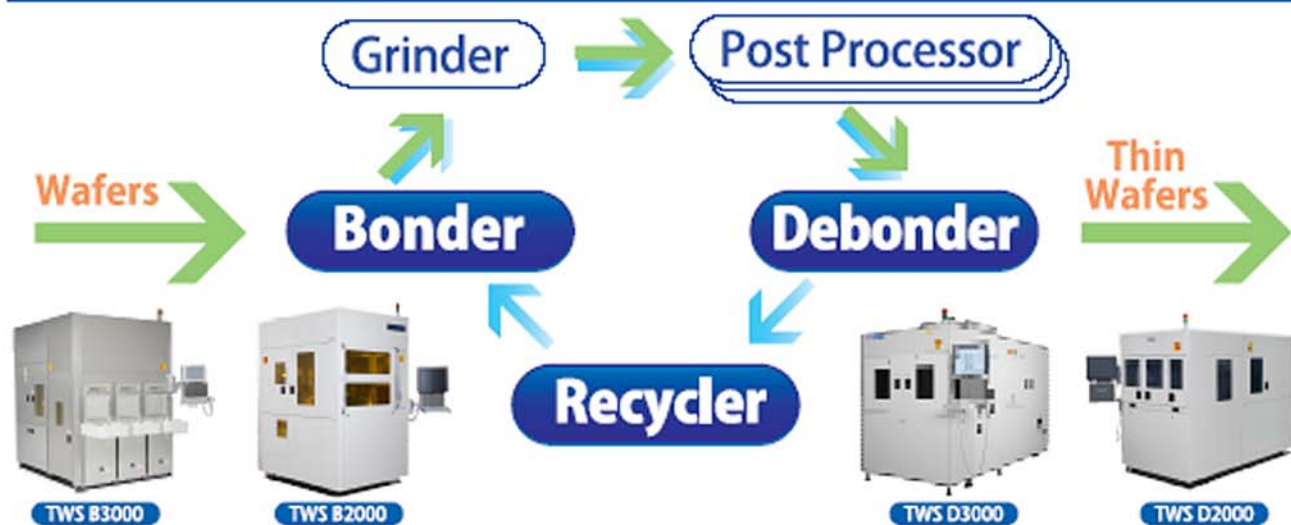
This system was designed for temporarily bonding of ultra thin wafer for advanced 3D packaging requirement. Unique UV hardening resin is used for the bonding of wafer and supporting material realizing excellent TTV, high accuracy alignment, normal temperature bonding and high throughput. The system have already introduced to Memory device, Power device and also other various production lines and achieving low CoO for the mass production.

● Features

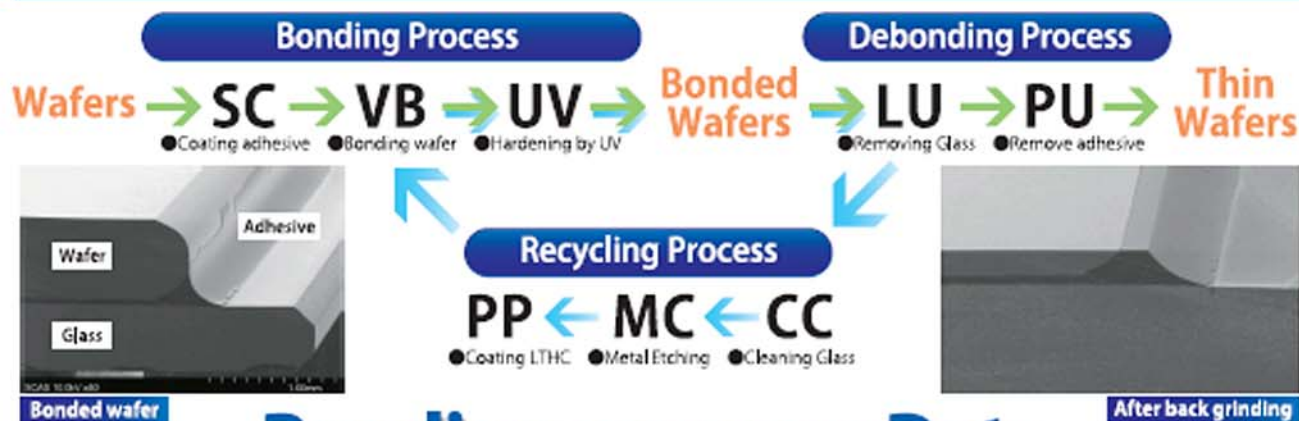
- **High throughput** ... realized >24 WPH
- **High accuracy** ... achieving TTV(Total Thickness Variation) < 3 μ m
- **Normal temperature bonding** ... Almost no thermal impact to the wafer when bonding with supporting material by adopting UV hardening resin.
- **Low cost** ... Repeated use of supporting material is possible thus used glass recycling tool is also line upped.
- **Dry process** ... Bonding, de-bonding of supporting material is performed by all dry process and no organic solvent are used.



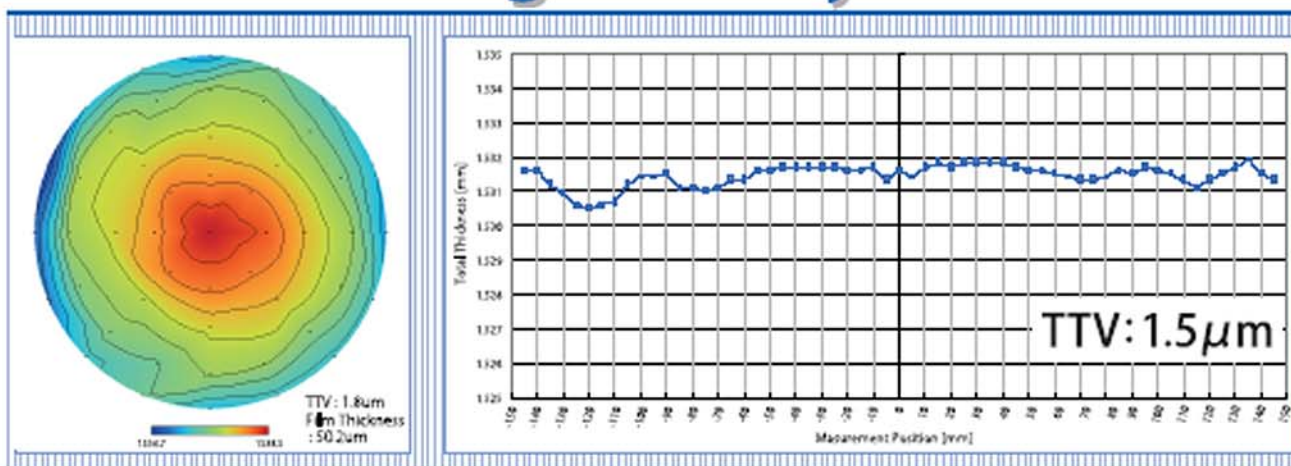
Wafer Support System Process Flow



Unit Process Flow



Bonding accuracy Data



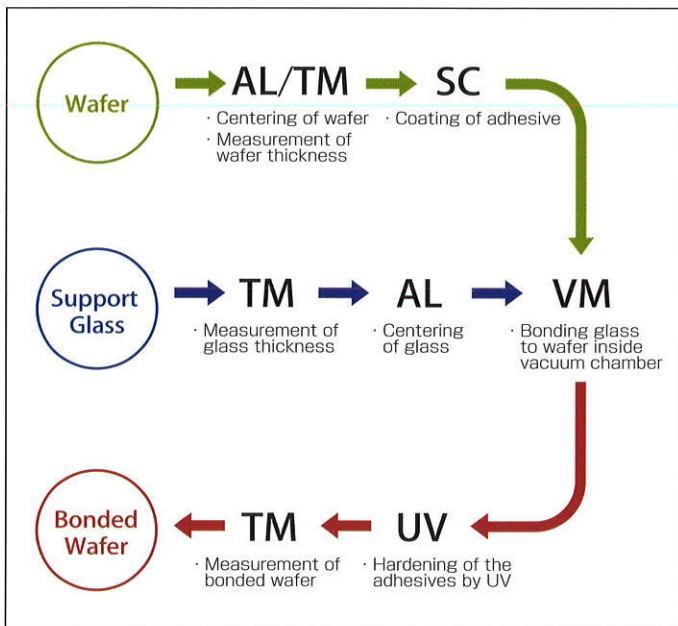
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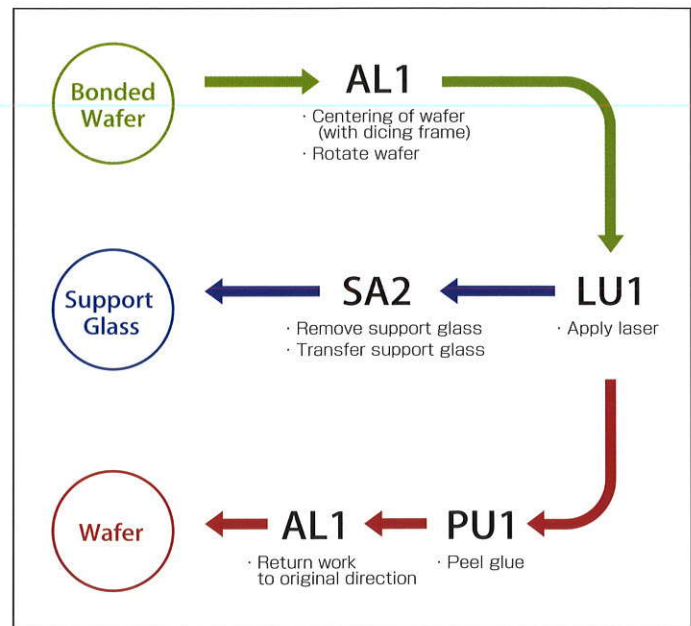


● System Process Flow

● Bonder [TWS B3000]



● Debonder [TWS D3000]



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